

MECHANICAL CASE OUTLINE

PACKAGE DIMENSIONS

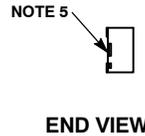
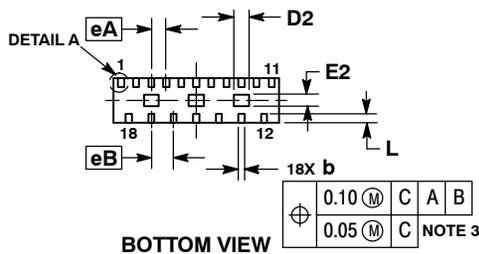
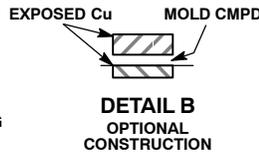
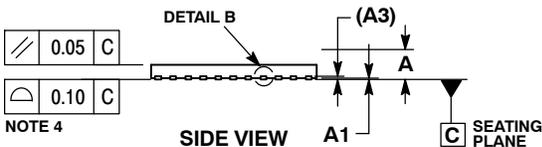
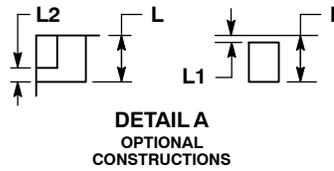
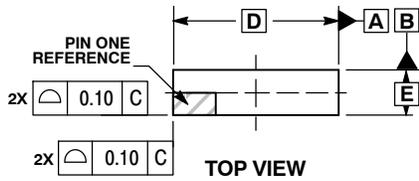
ON Semiconductor®



SCALE 2:1

UDFN18, 5.5x1.5, 0.5P
CASE 517BV
ISSUE A

DATE 11 DEC 2012



- NOTES:
1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
 2. CONTROLLING DIMENSION: MILLIMETERS.
 3. DIMENSION b APPLIES TO PLATED TERMINAL AND IS MEASURED BETWEEN 0.10 AND 0.20 MM FROM TERMINAL TIP.
 4. COPLANARITY APPLIES TO THE EXPOSED PAD AS WELL AS THE TERMINALS.
 5. EXPOSED ENDS OF TERMINALS ARE ELECTRICALLY ACTIVE.

DIM	MILLIMETERS	
	MIN	MAX
A	0.45	0.55
A1	0.00	0.05
A3	0.13	REF
b	0.15	0.25
D	5.50 BSC	
D2	0.45	0.55
E	1.50 BSC	
E2	0.35	0.45
eA	0.50 BSC	
eB	0.75 BSC	
L	0.20	0.40
L1	0.00	0.05
L2	0.10 REF	

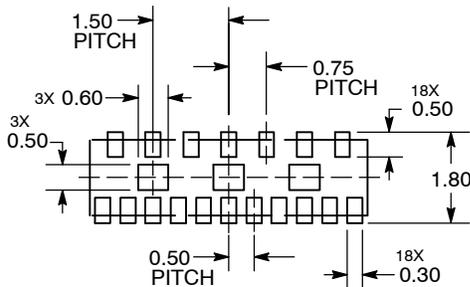
GENERIC MARKING DIAGRAM*



- XXXX = Specific Device Code
M = Date Code
■ = Pb-Free Package

*This information is generic. Please refer to device data sheet for actual part marking.

RECOMMENDED SOLDERING FOOTPRINT*



DIMENSION: MILLIMETERS

*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

DOCUMENT NUMBER:	98AON55750E	Electronic versions are uncontrolled except when accessed directly from the Document Repository. Printed versions are uncontrolled except when stamped "CONTROLLED COPY" in red.
STATUS:	ON SEMICONDUCTOR STANDARD	
NEW STANDARD:		
DESCRIPTION:	UDFN18, 5.5X1.5, 0.5P	PAGE 1 OF 2

